

PATENT ASSIGNMENT

Electronic Version v08
 Stylesheet Version v02

SUBMISSION TYPE:		NEW ASSIGNMENT		APPLICATION NUMBER 11/307532	
NATURE OF CONVEYANCE:		ASSIGNMENT OF ASSIGNOR'S INTEREST			
CONVEYING PARTY DATA					
Name		Execution Date			
Sangkwon Lee		2006-02-03			
Tae Keun Lee		2006-02-03			
RECEIVING PARTY DATA					
Name	Street Address	Internal Address	City	State/Country	Postal Code
STATS ChipPAC Ltd.	5 Yishun Street 23		Singapore	SINGAPORE	768442
CORRESPONDENCE DATA					
FAX NUMBER: 4087380881					
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>					
When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.					
CUSTOMER NUMBER: 022898					
NAME OF PERSON SIGNING:		Mikio Ishimaru			
DATE SIGNED:		2006-02-10			
Total Attachments: 2 source=27-155-Assign1.tif source=27-155-Assign2.tif					

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ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

HEAT DISSIPATING INTEGRATED CIRCUIT PACKAGE SYSTEM

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 5 Yishun Street 23, Singapore 768442 (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):


1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.

2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.

3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.

4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.


Sangkwon Lee

Feb 03, 2006
Date


Witness Signature


Witness Signature

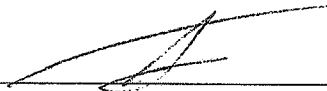
Soo San Park
Print Witness Name

Sung Ho Lee
Print Witness Name


Feb 3 '06
Date

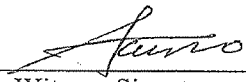
Feb 3 '06
Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.


Tae Keun Lee

2006 Feb 03
Date


Witness Signature


Witness Signature

Soo San Park
Print Witness Name

Sung Ho Lee
Print Witness Name

Feb 3 '06
Date

Feb 3 '06
Date